

Multilayer Ceramic Chip Capacitors

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CGA4J1X8R1E105K125AC



TDK item description ? CGA4J1X8R1E105KT****

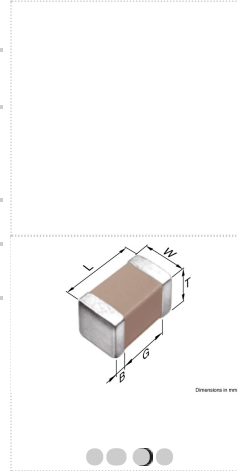
Applications Automotive Grade

Feature High Temperature Application

AEC-Q200

Series CGA4(2012) [EIA 0805]

Status Production



Images are for reference only and show exemplary products.

PDF file of this page

Contact

Documents

- Catalog
- Specification
- RoHS Certificate
- SVHC/REACH Certificate
- Promotion Video
- Sample Kits

Size

Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics

Capacitance	1μF ±10%
Rated Voltage	25VDC
Temperature Characteristic ?	X8R(±15%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	500MΩ

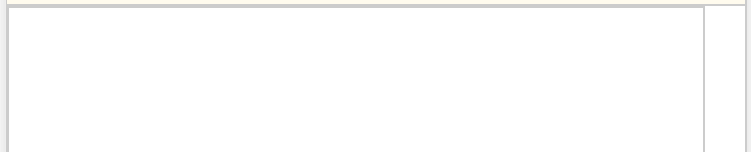
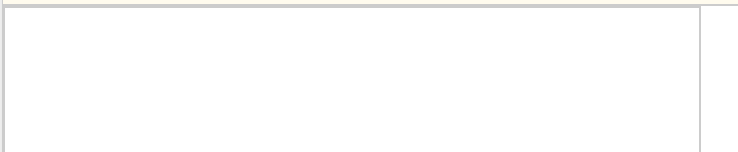
Other

Soldering Method	Wave (Flow) Reflow
AEC-Q200	Yes
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

Impedance

ESR



no data available

Change settings

no data available

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Capacitance

no data available

Change settings

DC Bias Characteristic

no data available

Change settings

Temperature Characteristic

no data available

Change settings

Ripple Temperature Rising

no data available

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- » RF Components and Modules
- » Voltage / Current / Temperature Protection Devices
- » Sensors and Sensor Systems
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- » Transformers
- » Ferrites and Accessories
- » Noise Suppressing / Magnetic Sheet
- » Anechoic Chambers and Radio Wave Absorbers
- » Power Supplies
- » Magnets
- » Flash Storages
- » Wireless Power Transfer
- » FA Systems
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